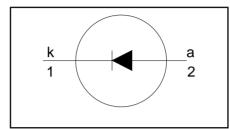
# BYV29F, BYV29X series

#### **FEATURES**

- Low forward volt drop
- Fast switching
- · Soft recovery characteristic
- High thermal cycling performance
- · Isolated mounting tab

#### **SYMBOL**



#### QUICK REFERENCE DATA

$$V_R = 300 \text{ V/ } 400 \text{ V/ } 500 \text{ V}$$
 $V_F \le 1.03 \text{ V}$ 
 $I_{F(AV)} = 9 \text{ A}$ 
 $t_{rr} \le 60 \text{ ns}$ 

#### **GENERAL DESCRIPTION**

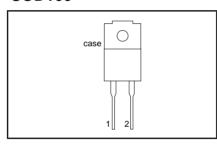
Ultra-fast epitaxial rectifier diodes intended for use in switched mode power supply output rectification, electronic lighting ballasts and high frequency switching circuits in general.

The BYV29F series is supplied in the SOD100 package. The BYV29X series is supplied in the SOD113 package.

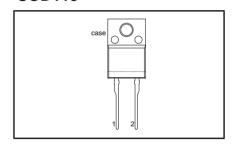
#### **PINNING**

PIN	DESCRIPTION		
1	cathode (k)		
2	anode (a)		
tab	isolated		

#### **SOD100**



### **SOD113**



## **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
$V_{RRM} \ V_{R}$	Peak repetitive reverse voltage Continuous reverse voltage	$\label{eq:BYV29F/BYV29X} \textbf{T}_{hs} \leq 138^{\circ}\textbf{C}^{1}$	-	<b>-300</b> 300 300	<b>-400</b> 400 400	<b>-500</b> 500 500	V
I <sub>F(AV)</sub>	Average forward current <sup>2</sup>	square wave; $\delta = 0.5$ ; $T_{hs} \leq 90  ^{\circ}C$	-		9		A
I <sub>FSM</sub>	Non-repetitive peak forward current	t = 10 ms t = 8.3 ms sinusoidal; with reapplied	-		100 110		A A
$egin{array}{c} T_{stg} \ T_{j} \end{array}$	Storage temperature Operating junction temperature	V <sub>RRM(max)</sub>	-40 -		150 150		°C °C

<sup>1</sup> T<sub>hs</sub> de-rating for thermal stability.

<sup>2</sup> Neglecting switching and reverse current losses

BYV29F, BYV29X series

# **ISOLATION LIMITING VALUE & CHARACTERISTIC**

 $T_{hs}$  = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	Peak isolation voltage from all terminals to external heatsink	SOD100 package; R.H. ≤ 65%; clean and dustfree	ı	1	1500	٧
V <sub>isol</sub>	R.M.S. isolation voltage from all terminals to external heatsink	SOD113 package; f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	1	1	2500	V
C <sub>isol</sub>	Capacitance from pin 2 to external heatsink	f = 1 MHz	-	10	-	pF

# THERMAL RESISTANCES

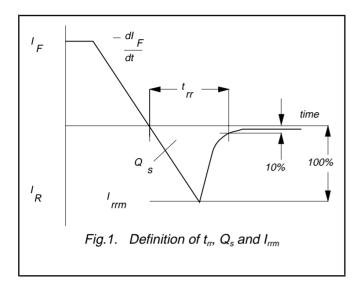
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	heatsink	with heatsink compound without heatsink compound in free air.	- - -	- - 55	5.5 7.2 -	K/W K/W K/W

# **ELECTRICAL CHARACTERISTICS**

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	Forward voltage	$I_{\rm F} = 8 \text{ A}; T_{\rm i} = 150^{\circ}\text{C}$	-	0.90	1.03	V
		$I_F = 8 \text{ A}$	-	1.05	1.25	V
		$I_{\rm F} = 20  \text{A}$	-	1.20	1.40	V
l <sub>R</sub>	Reverse current	$V_R = V_{RRM}$	-	2.0	50	μΑ
		$V_{R} = V_{RRM}$ ; $T_{i} = 100  ^{\circ}$ C	-	0.1	0.35	mΑ
$Q_s$	Reverse recovery charge	$I_{\rm F} = 2 \text{ A to } V_{\rm R} \ge 30 \text{ V};$	-	40	60	nC
		$dI_F/dt = 20 A/\mu s$				
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A to } V_R \ge 30 \text{ V};$	-	50	60	ns
		$dI_F/dt = 100 A/\mu s$				_
I <sub>rrm</sub>	Peak reverse recovery current	$I_{\rm F} = 10 \text{ A to V}_{\rm R} \ge 30 \text{ V};$	-	4.0	5.5	Α
		$dI_{F}/dt = 50 \text{ A/µs}; T_{j} = 100^{\circ}\text{C}$				
$V_{fr}$	Forward recovery voltage	$I_F = 10 \text{ A}, dI_F/dt = 10 \text{ A}/\mu\text{s}$	-	2.5	-	V

# BYV29F, BYV29X series



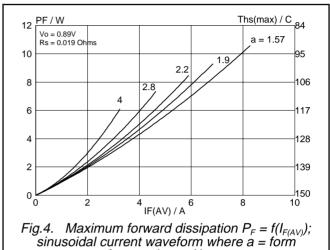
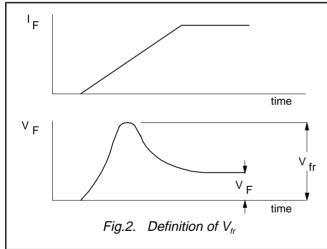
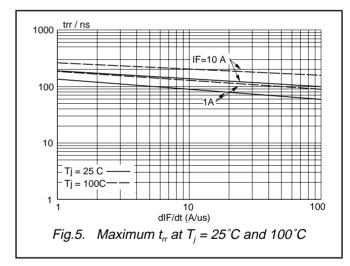
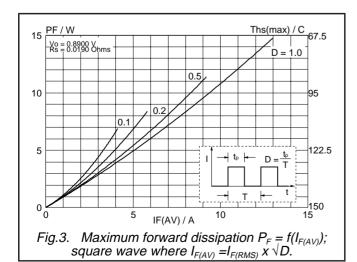
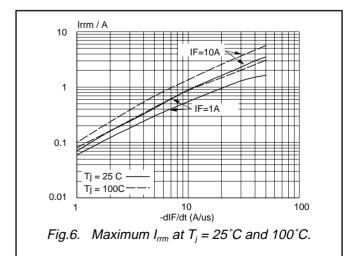


Fig.4. Maximum forward dissipation  $P_F = f(I_{F(AV)})$ ; sinusoidal current waveform where a = form factor =  $I_{F(RMS)} / I_{F(AV)}$ .

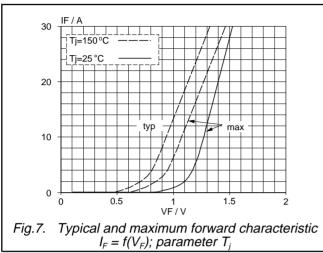


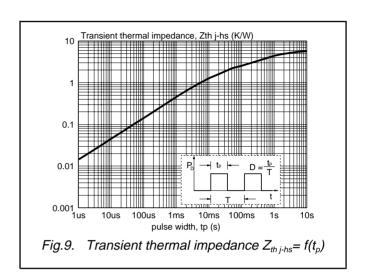


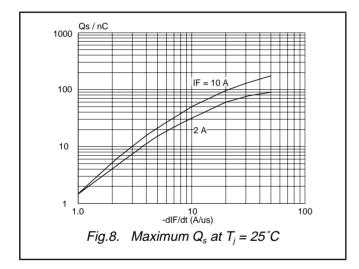




# BYV29F, BYV29X series

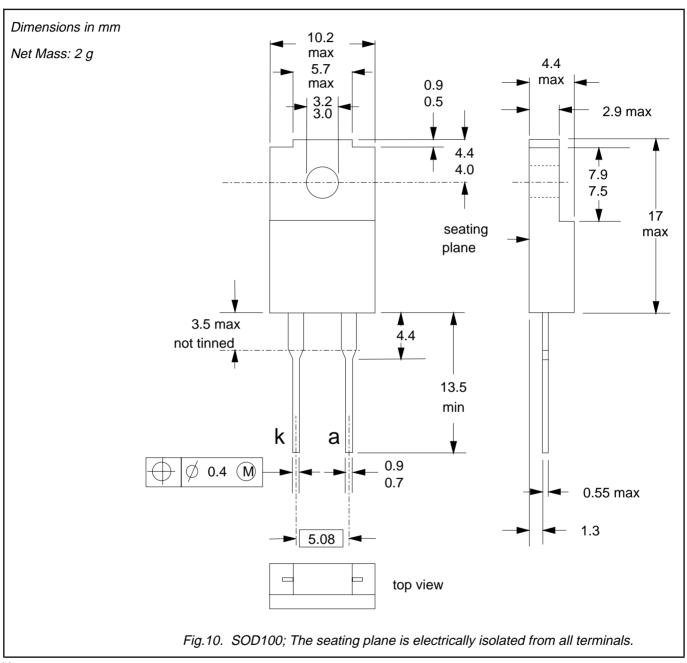






BYV29F, BYV29X series

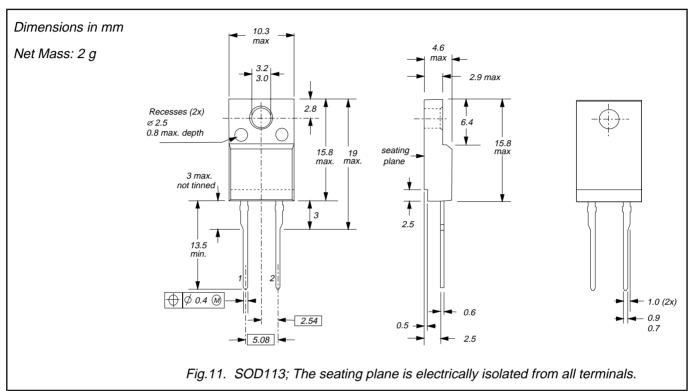
# **MECHANICAL DATA**



- Refer to mounting instructions for F-pack envelopes.
   Epoxy meets UL94 V0 at 1/8".

BYV29F, BYV29X series

# **MECHANICAL DATA**



# **Notes**

- Refer to mounting instructions for F-pack envelopes.
   Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

# Rectifier diodes ultrafast

BYV29F, BYV29X series

#### **DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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